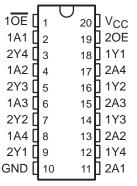


SCAS343E - MARCH 1994 - REVISED JUNE 1998

- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 2 V at V_{CC} = 3.3 V, T_A = 25°C
- Power Off Disables Outputs, Permitting Live Insertion
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages

DB, DW, OR PW PACKAGE (TOP VIEW)



description

This octal buffer/line driver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVC241A is designed specifically to improve both the performance and density of 3-state memory-address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the $^{\prime}$ LVC240A and $^{\prime}$ LVC244A, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical $\overline{\text{OE}}$ (active-low output-enable) inputs, and complementary OE and $\overline{\text{OE}}$ inputs.

The SN74LVC241A is organized as two 4-bit line drivers with separate output-enable $(1\overline{OE}, 2OE)$ inputs. When $1\overline{OE}$ is low or 2OE is high, the device passes data from the A inputs to the Y outputs. When $1\overline{OE}$ is high or 2OE is low, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking or the current-sourcing capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

The SN74LVC241A is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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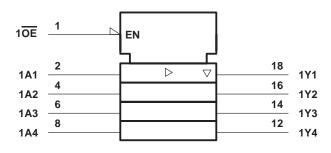


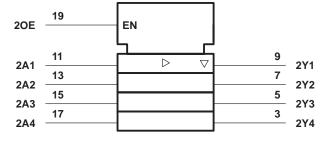
FUNCTION TABLES

INPU	JTS	OUTPUT
1OE	1A	1Y
L	Н	Н
L	L	L
н	Χ	Z

INP	UTS	OUTPUT
20E	2A	2Y
Н	Н	Н
Н	L	L
L	Χ	Z

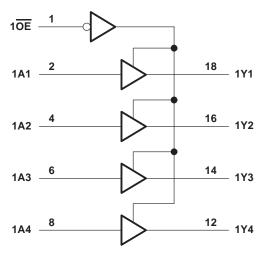
logic symbol†

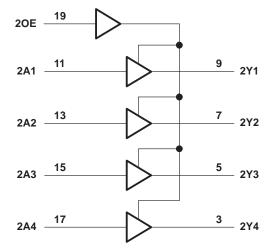




[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)







absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 6.5 V
Input voltage range, V _I (see Note 1)		0.5 V to 6.5 V
Voltage range applied to any output in the high	-impedance or power-off state, VO	
(see Note 1)		0.5 V to 6.5 V
Voltage range applied to any output in the high	or low state, V _O	
(see Notes 1 and 2)		0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)		
Output clamp current, I _{OK} (V _O < 0)		
Continuous output current, IO		
Continuous current through V _{CC} or GND		
Package thermal impedance, θ_{JA} (see Note 3):		
,	DW package	97°C/W
	PW package	
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of V_{CC} is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Voc	Supply voltage	Operating	1.65	3.6	V
Vcc	Supply voltage	Data retention only	1.5		v
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
VIH	VIH High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		V _{CC} = 2.7 V to 3.6 V	2		
	V _{IL} Low-level input voltage	V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	
VIL		V _{CC} = 2.3 V to 2.7 V		0.7	V
		V _{CC} = 2.7 V to 3.6 V		0.8	
٧ _I	Input voltage		0	5.5	V
V	Output valtage	High or low state	0	Vcc	V
VO	Output voltage	3 state	0	5.5	V
		V _{CC} = 1.65 V		-4	
la	High lovel cutout current	V _{CC} = 2.3 V		-8	A
ЮН	High-level output current	V _{CC} = 2.7 V		-12	mA
		V _{CC} = 3 V		-24	
		V _{CC} = 1.65 V		4	
	Low-level output current	V _{CC} = 2.3 V		8	A
IOL		V _{CC} = 2.7 V		12	mA
		V _{CC} = 3 V		24	
Δt/Δν	Input transition rise or fall rate		0	10	ns/V
T _A	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDI	Vcc	MIN	TYP [†]	MAX	UNIT	
	$I_{OH} = -100 \mu\text{A}$		1.65 V to 3.6 V	V _{CC} -0.2			
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2				
Vou	$I_{OH} = -8 \text{ mA}$		2.3 V	1.7			v
VOH	I _{OH} = -12 mA		2.7 V	2.2			V
	10H = -12 IIIA		3 V	2.4			
	I _{OH} = -24 mA		3 V	2.2			
	I _{OL} = 100 μA		1.65 V to 3.6 V			0.2	
	I _{OL} = 4 mA					0.45	
VOL	I _{OL} = 8 mA		2.3 V			0.7	V
	I _{OL} = 12 mA	2.7 V			0.4		
	I _{OL} = 24 mA		3 V			0.55	
lį	V _I = 0 to 5.5 V	V _I = 0 to 5.5 V				±5	μΑ
l _{off}	V_I or $V_O = 5.5 V$	V_I or $V_O = 5.5 V$				±10	μΑ
loz	V _O = 0 to 5.5 V		3.6 V			±10	μΑ
	V _I = V _{CC} or GND				-	10	
lcc	$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{\ddagger}$	IO = 0	3.6 V			10	μΑ
ΔlCC	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND		2.7 V to 3.6 V			500	μА
Ci	$V_I = V_{CC}$ or GND		3.3 V			·	pF
Co	$V_O = V_{CC}$ or GND		3.3 V		-		pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ This applies in the disabled state only.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =	1.8 V 5 V	V _{CC} =	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	А	Υ									ns
t _{en}	OE or OE	Υ									ns
t _{dis}	OE or OE	Υ									ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V ± 0.15 V	V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT	
		CONDITIONS	TYP	TYP	TYP		
C _{pd}	Power dissipation capacitance	Outputs enabled	f = 10 MHz				pF
Opa	per buffer/driver	Outputs disabled	1 = 10 MH2				pr

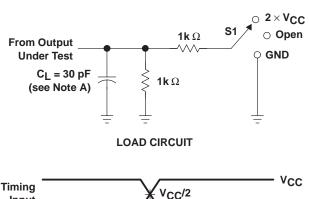


VCC

0 V

V_{CC}/2

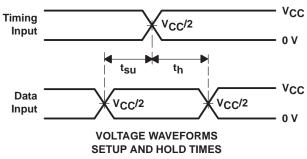
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

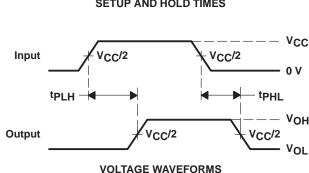


TEST	S1
t _{pd}	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	Open

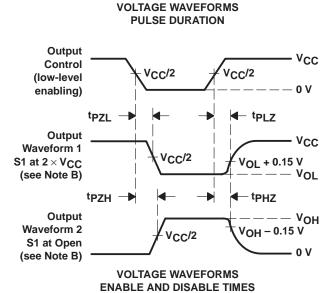
V_{CC}/2

Input





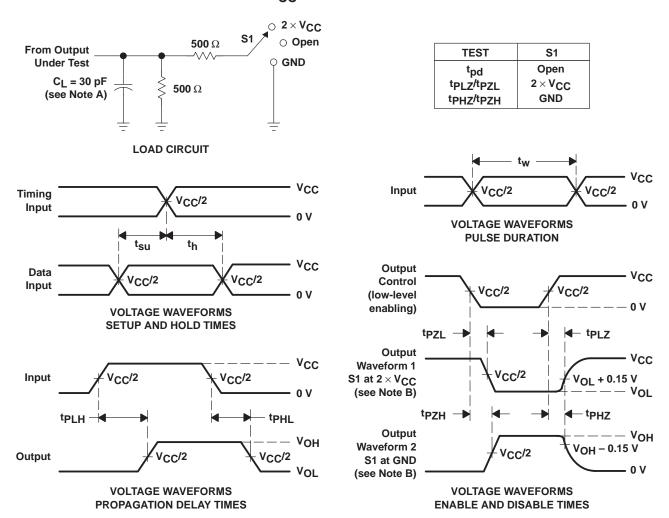
PROPAGATION DELAY TIMES



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f\leq$ 2 ns. $t_f\leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 V \pm 0.2 V$



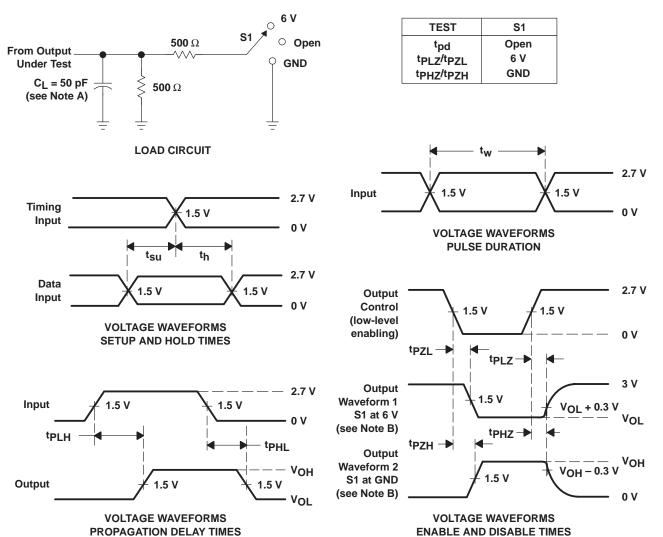
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f\leq$ 2 ns, $t_f\leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tplH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PRODUCT PREVIEW

PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

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